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Journal Name:	**Journal of Engineering Research and Reports**
Manuscript Number:	**Ms_JERR_68102**
Title of the Manuscript:	**Proactive Verification of Strip Y-Index to Mitigate Gross Misaligned Cut due to Mismatched Unit Pitching**
Type of the Article	**Original Research Article**

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty'**, provided the manuscript is scientifically robust and technically sound.
To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(http://www.sciencedomain.org/journal/10/editorial-policy)

PART 1: **Review Comments**

	Reviewer's comment	**Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)*
Compulsory REVISION comments	**1. Some grammatical mistakes are found. Please have a proofing by a native speaker.** **2. The problem is not well explained about the strategies to avoid mismatched unit pitching.** **3. As mentioned in the Abstract, it is a good point that this problem has been encountered in semiconductor assembly. However, the authors do not explicitly discuss this further in the main text. Some references are suggested for the authors about the reliability due to mismatch of thermal expansion: Constitutive behaviour and life evaluation of solder joint under the multi-field loadings; Thermal fatigue life of Sn–3.0 Ag–0.5 Cu solder joint under temperature cycling coupled with electric current; Mechanics-based acceleration for estimating thermal fatigue life of electronic packaging structure.** **4. No literature review has been given in the Introduction. It is strongly suggested to the authors to make a review based on latest publications.** **5. Defect could be a general issue for the manufacturing industry. This could be relevant to the mechanical properties of the products. More info could be found in the paper: Mechanical effects of isolated defects within a lead-free solder bump subjected to coupled thermal-electrical loading; Strain rate shift for constitutive behaviour of sintered silver nanoparticles under nanoindentation.** **6. Important findings should be further emphasized in the Conclusion.**	
Minor REVISION comments		
Optional/General comments		

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PART 2:

	Reviewer's comment	**Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)*
Are there ethical issues in this manuscript?	*(If yes, Kindly please write down the ethical issues here in details)*	

Reviewer Details:

Name:	*Xu Long*
Department, University & Country	*Northwestern Polytechnical University, China*